

General Features

- Low On-Resistance
- 100% avalanche tested
- Fast Switching Speed
- Excellent package for good heat dissipation

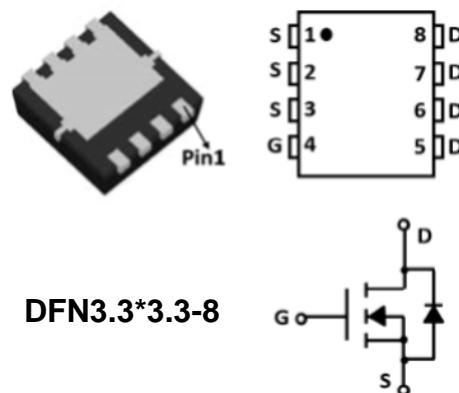
Product Summary



V_{DS}	40	V
$R_{DS(on),TYP} @ V_{GS}=10\text{ V}$	4.2	mΩ
I_D	52	A

Application

- DC/DC Converters
- On board power for server
- Synchronous rectification



Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		40	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_c = 25^\circ\text{C}$	52	A
		$T_c = 100^\circ\text{C}$	35	A
I_{DM}	Pulsed Drain Current ^{note1}		220	A
EAS	Single Pulsed Avalanche Energy ^{note2}		100	mJ
P_D	Power Dissipation	$T_c = 25^\circ\text{C}$	65	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		1.92	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

Electrical Characteristics ($T_C=25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Condition	ASDM40N52E			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{DS}}=250\mu\text{A}$	40			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}$			1	μA
		$T_J=125^\circ\text{C}$			30	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{DS}}=250\mu\text{A}$	1	1.6	2.5	V
I_{GSS}	Gate Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$			± 100	nA
$R_{\text{DS(ON)}}^{\text{(1)}}$	Drain-Source On-state Resistance	$V_{\text{GS}}=4.5\text{V}, I_{\text{DS}}=20\text{A}$		6.0	10	$\text{m}\Omega$
		$V_{\text{GS}}=10\text{V}, I_{\text{DS}}=30\text{A}$		4.2	5.5	$\text{m}\Omega$
Diode Characteristics						
$V_{\text{SD}}^{\text{(1)}}$	Diode Forward Voltage	$I_{\text{SD}}=26\text{A}, V_{\text{GS}}=0\text{V}$			1.2	V
t_{rr}	Reverse Recovery Time	$I_{\text{SD}}=26\text{A}, dI_{\text{SD}}/dt=100\text{A}/\mu\text{s}$		14		ns
Q_{rr}	Reverse Recovery Charge			32		nC
Dynamic Characteristics ⁽²⁾						
R_{G}	Gate Resistance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$		2.6		Ω
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=20\text{V}, \text{Frequency}=1.0\text{MHz}$		3500		pF
C_{oss}	Output Capacitance			267		
C_{rss}	Reverse Transfer Capacitance			240		
$t_{\text{d(ON)}}$	Turn-on Delay Time	$V_{\text{DD}}=20\text{V}, I_{\text{DS}}=26\text{A}, V_{\text{GS}}=10\text{V}, R_{\text{G}}=4.7\Omega$		6		ns
t_{r}	Turn-on Rise Time			10		
$t_{\text{d(OFF)}}$	Turn-off Delay Time			24		
t_{f}	Turn-off Fall Time			5		
Gate Charge Characteristics ⁽²⁾						
Q_{g}	Total Gate Charge	$V_{\text{DS}}=32\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{DS}}=26\text{A}$		18	23	nC
Q_{gs}	Gate-Source Charge			2.5		
Q_{gd}	Gate-Drain Charge			5		

Notes:

⁽¹⁾Pulse test; Pulse width $\leqslant 300\mu\text{s}$, duty cycle $\leqslant 2\%$.

⁽²⁾Guaranteed by design, not subject to production testing.

Test Circuit

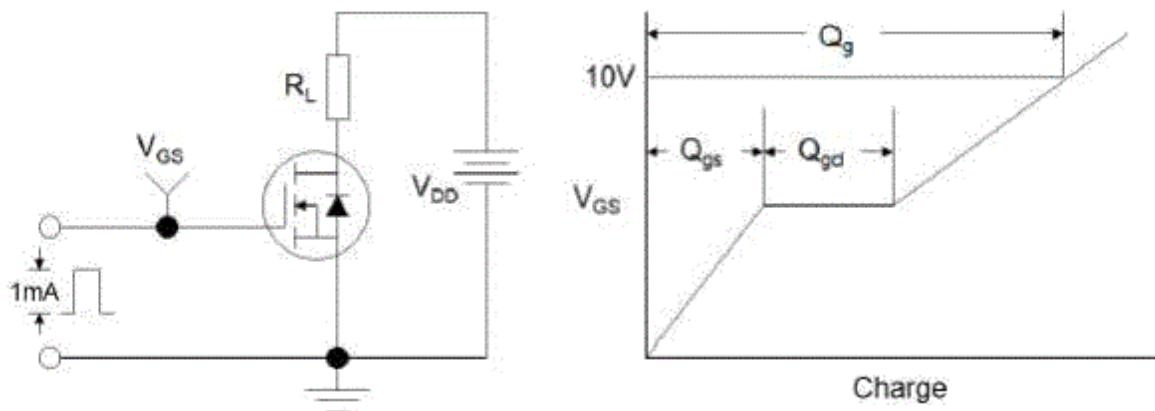


Figure1:Gate Charge Test Circuit & Waveform

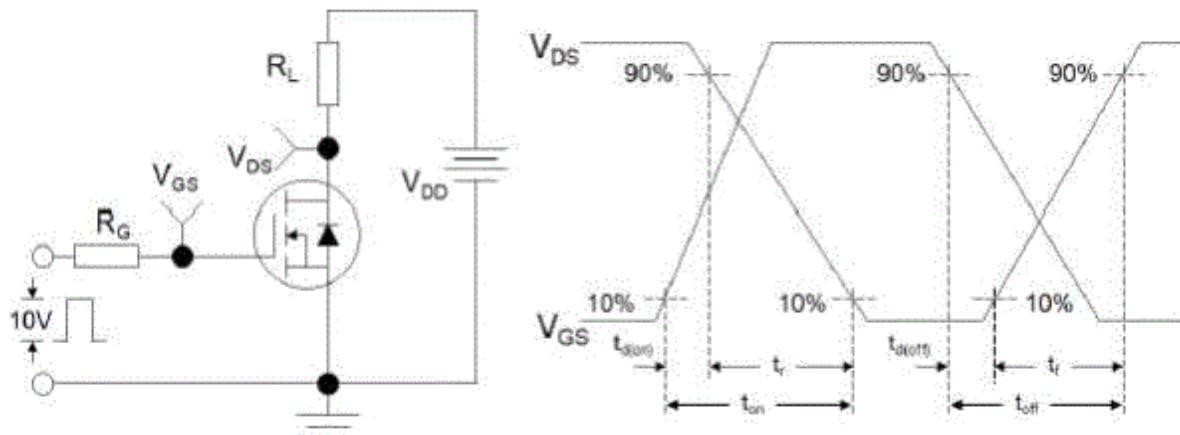


Figure 2: Resistive Switching Test Circuit & Waveforms

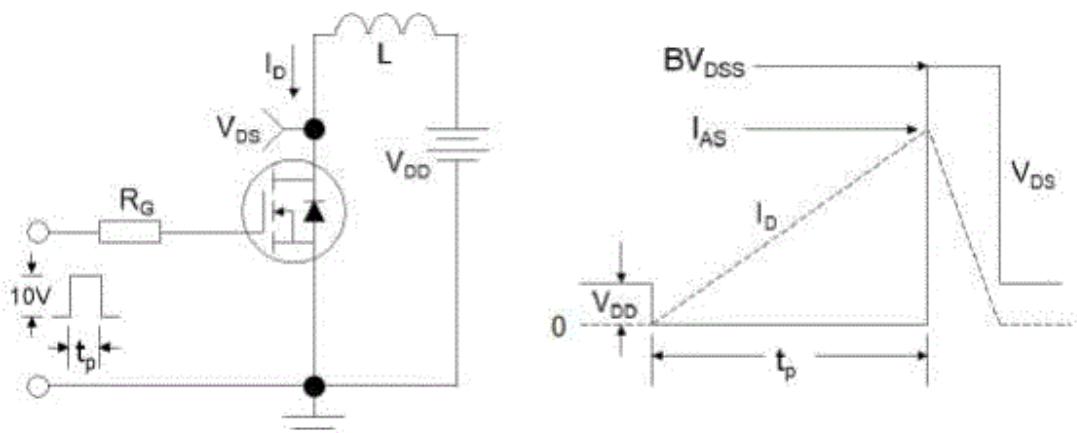
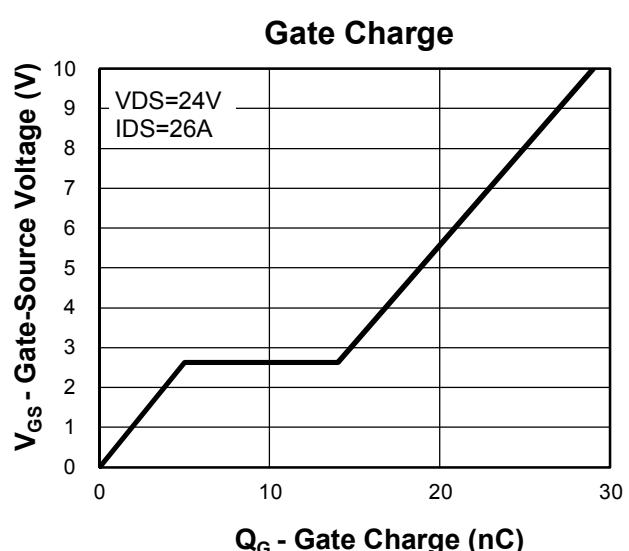
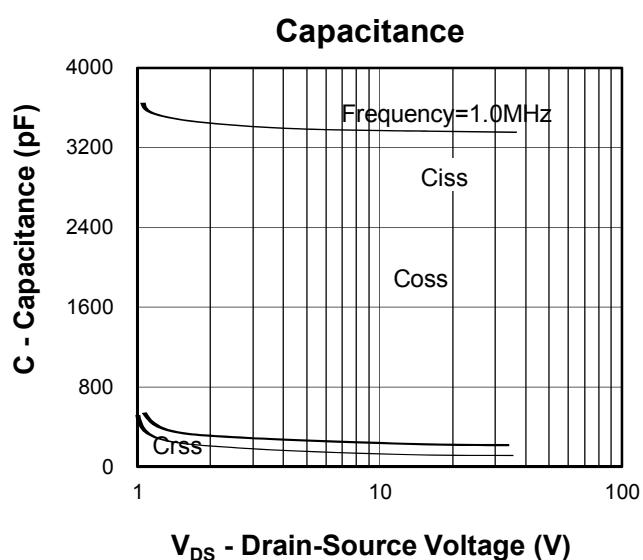
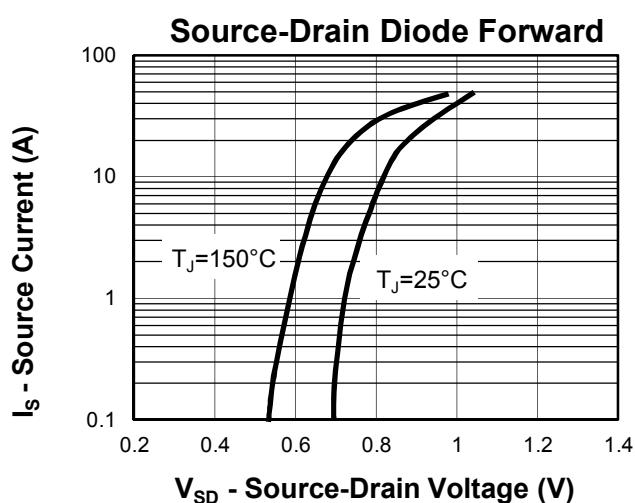
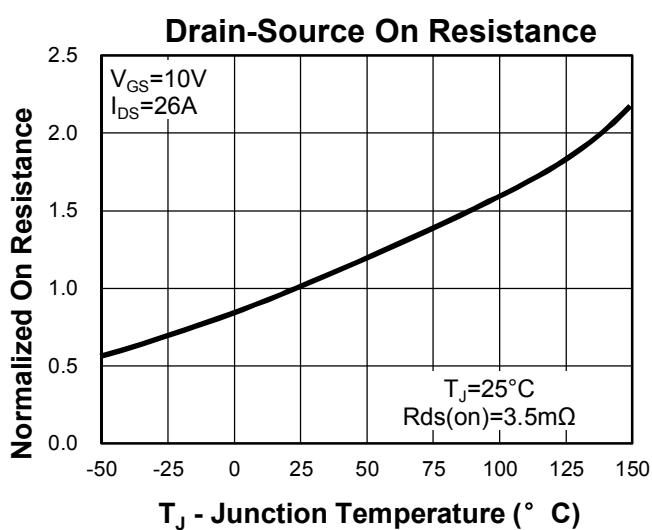
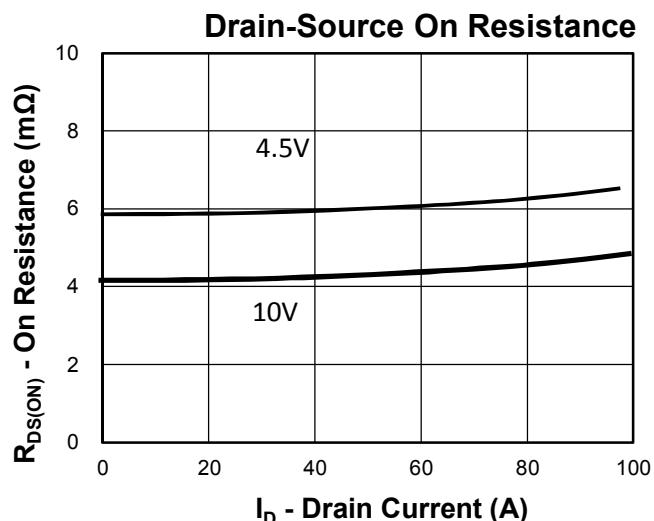
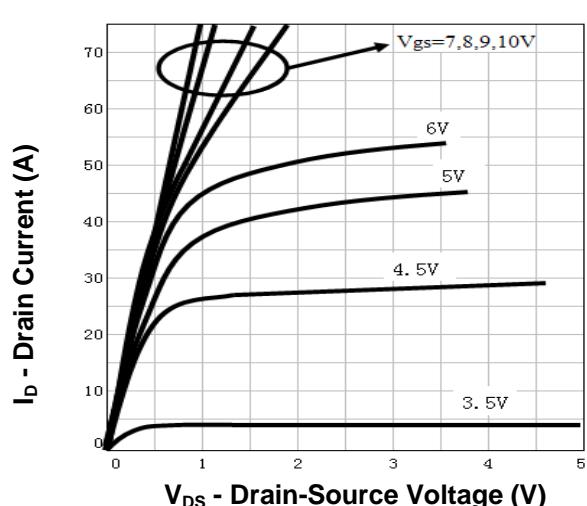
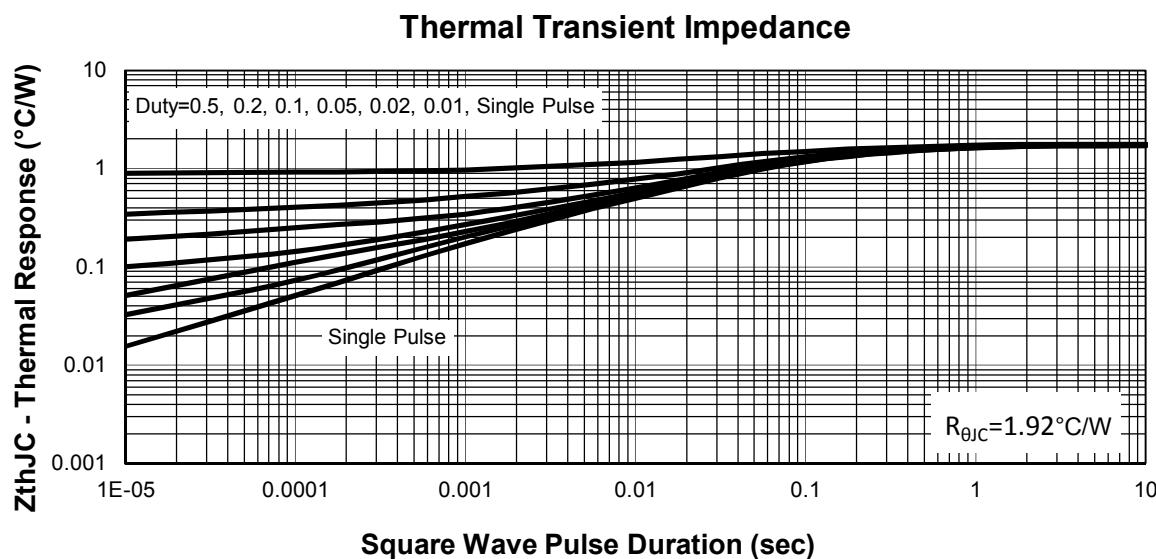
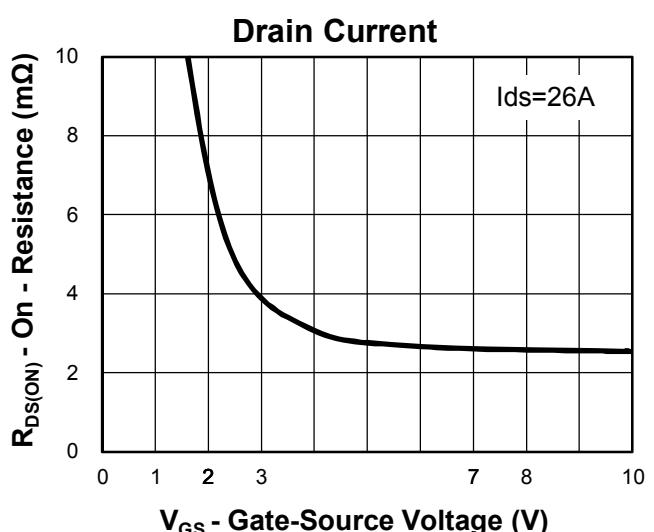
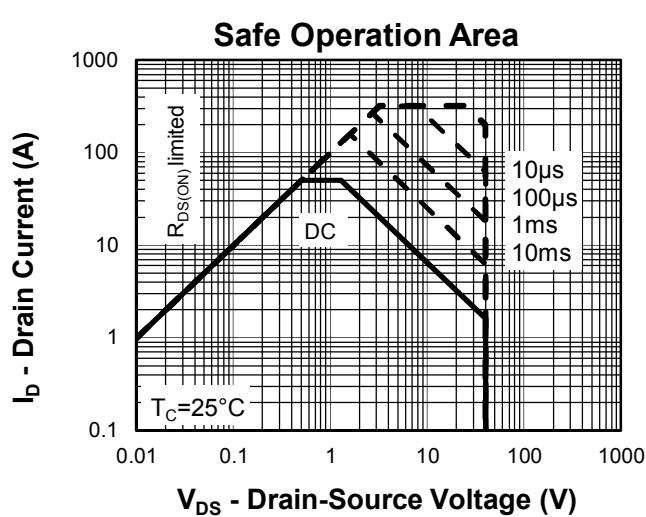
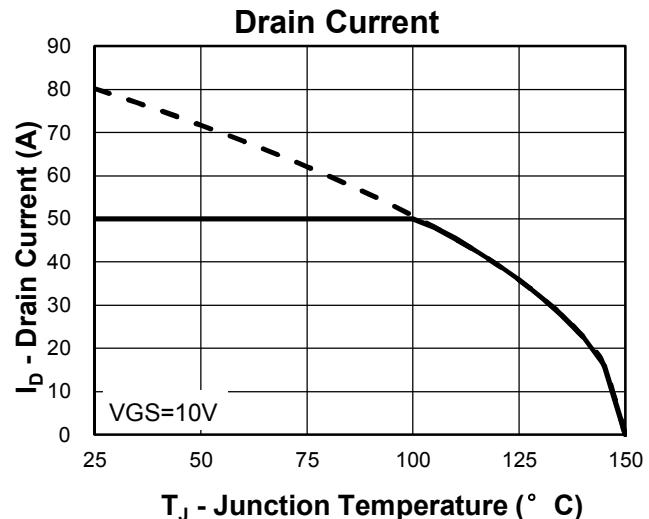
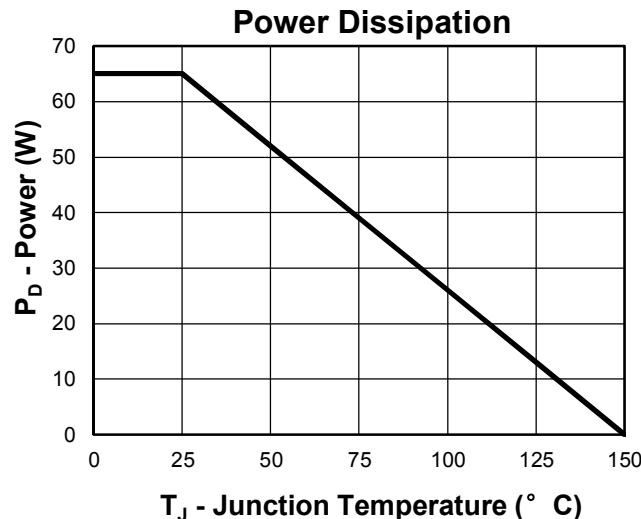


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

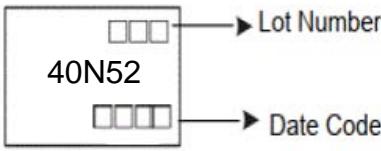
Typical Electrical and Thermal Characteristics (Curves)



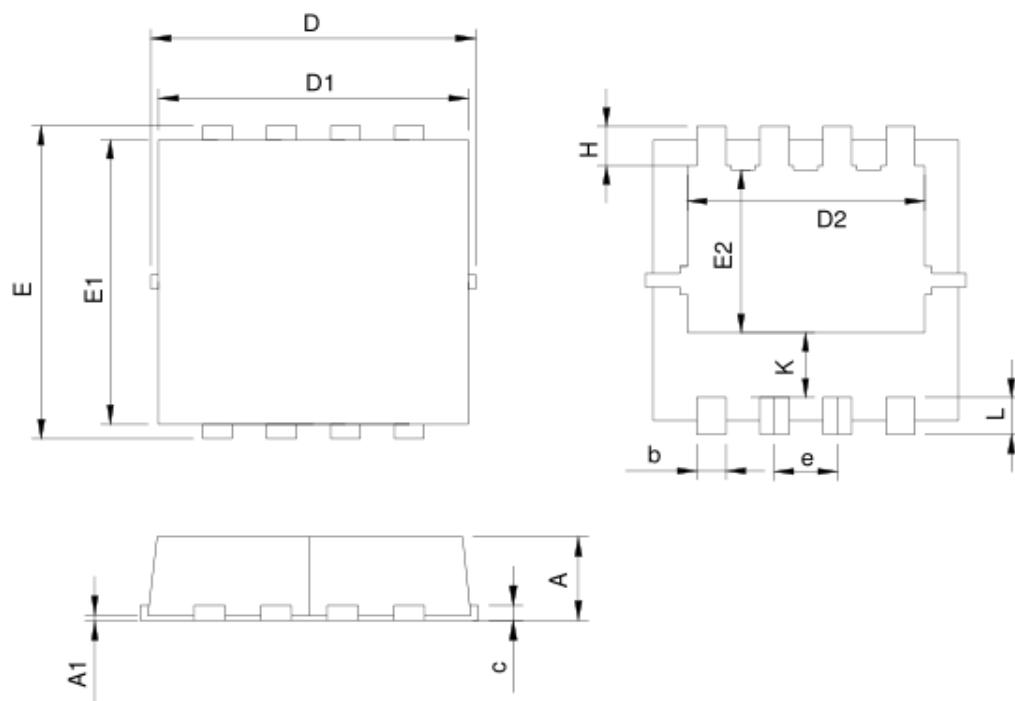


Ordering and Marking Information

Ordering Device No.	Marking	Package	Packing	Quantity
JM3N40N52E-R	40N52	DFN3.3x3.3-8	Tape&Reel	5000/Reel

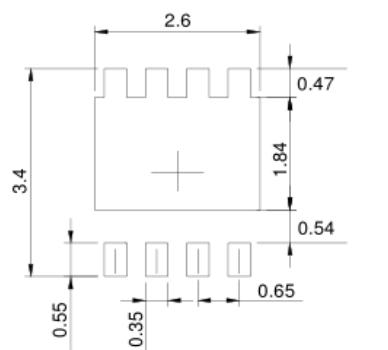
PACKAGE	MARKING
DFN3.3x3.3-8	 Lot Number 40N52 Date Code

Dimensions(DFN3.3x3.3-8)



SYMBOL	DFN3.3x3.3-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.70	1.00	0.028	0.039
A1	0.00	0.05	0.000	0.002
b	0.25	0.35	0.010	0.014
c	0.14	0.20	0.006	0.008
D	3.10	3.50	0.122	0.138
D1	3.05	3.25	0.120	0.128
D2	2.35	2.55	0.093	0.100
E	3.10	3.50	0.122	0.138
E1	2.90	3.10	0.114	0.122
E2	1.64	1.84	0.065	0.072
e	0.65 BSC		0.026 BSC	
H	0.32	0.52	0.013	0.020
K	0.59	0.79	0.023	0.031
L	0.25	0.55	0.010	0.022

RECOMMENDED LAND PATTERN



UNIT: mm

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